Electronic Supplementary Material (ESI) for Journal of Materials Chemistry C. This journal is © The Royal Society of Chemistry 2024

## **Supplementary Information**

**Thermogalvanic Organohydrogel-Based Non-Contact Self-Powered Electronics for Advancing Smart Agriculture**

Xinru Yang,<sup>a</sup> Zhiyi Zhang,<sup>b</sup> Saeed Ahmed Khan,<sup>c</sup> Lei Sun,<sup>a</sup> Zhaosu Wang,<sup>a</sup> Xiaojing Cui,<sup>d</sup> Zhiquan Huang<sup>\*e</sup> and Hulin Zhang<sup>\*a</sup>

<sup>a</sup>College of Electronic Information and Optical Engineering, Taiyuan University of

Technology, Taiyuan, 030024, China

<sup>b</sup>College of Materials Science and Engineering, Taiyuan University of Technology,

Taiyuan, 030024, China

<sup>c</sup>Department of Electrical Engineering, Sukkur IBA University, Sukkur 65200, Pakistan

dSchool of Physics and Information Engineering, Shanxi Normal University, Taiyuan 030031, China

<sup>e</sup>School of Mechanical Engineering, Taiyuan University of Science and Technology, Taiyuan, 030024, China

\*To whom correspondence should be addressed: [zhiquanhuang@tyust.edu.cn](mailto:zhiquanhuang@tyust.edu.cn)  $(Z.H.)$ ; zhanghulin@tyut.edu.cn (H.Z.)



**Fig. S1** SEM image of a PVA gel after freeze-drying (scale bar: 1 μm).



**Fig. S2** FTIR spectra of gels with different compositions.



**Fig. S3** A comprehensive comparison between the organohydrogel and the previously reported thermogalvanic hydrogels in terms of the comprehensive properties of Stress (kPa), Stretchability (%), Seebeck coefficient  $(S_e)$ , Recyclability and Anti-freezing.



**Fig. S4** Stress-Strain curves of the gel with different concentration of the DMSO.



**Fig. S5** Elastic stability of the DMSO/H2O and H2O hydrogel at 333K and subzero temperatures.



**Fig. S6** Stress-Strain curves of the gel under different temperatures.



**Fig. S7** DSC curves for gels with different compositions.



**Fig. S8** Dissipated energy values of organohydrogel at different tensile strains.



**Fig. S9** Photos showing the organohydrogel excellent compressive and recovery.



**Fig. S10** Infrared image of an organohydrogel exposed to sunlight for 120s (scale bar: 1cm).



**Fig. S11** Stress-Strain curves of the gel with different concentration of the CuSO4.



**Fig. S12** Electrical and thermal conductivity of organohydrogel at different temperatures.



**Fig. S13** Schematic image of the platform for thermopower measurements.



**Fig. S14** (a) Thermal current curve of the thermogalvanic gel at different temperatures. (b)Thermal currents in organohydrogel subjected to 30 cycles at ~15 K temperature difference.



**Fig. S15** The maximum output power density and normalized output power density curves under different ΔT values.



Fig. S16 Comparison of anti-drying capacity of the DMSO/H<sub>2</sub>O and H<sub>2</sub>O gel over 6

days at room temperature.

	Day 1	Day 2	Day 3	Day 4	Day 5	Day 6	Day 7
DMSO/H <sub>2</sub> O							
H <sub>2</sub> O							

**Fig. S17** Images of the DMSO/H2O and H2O gel at different different intervals (Scale bar: 1 cm).



**Fig. S18** TG and DTG curves of gels with or without DMSO.



**Fig. S19** Variation of open circuit voltage after being placed in the air for 6 days.



**Fig. S20** Recycling process of the organohydrogel. Scale bar 1 cm.



**Fig. S21** (a) A photograph of organohydrogel gel being pressed (scale bar: 10 mm). (b) Voltage-time and current-time curves of the organohydrogel gel being repeatedly pressed when  $Tc = 293$  K and  $Th = 308$  K. (c) A photograph of organohydrogel gel being stretched (scale bar: 10 mm). (d) Voltage-time and current-time curves of organohydrogel gel being epeatedly stretched when Tc= 293 K and Th= 308 K. (e) A photograph of organohydrogel gel being bent (scale bar: 10 mm). (f) Voltage-time and current-time curves of the organohydrogel gel being repeatedly bent when Tc= 293 K and Th= 308 K.



**Fig. S22** UV–vis–NIR reflection spectra of PDMS/CuO/Cu foil, CuO/Cu foil, and Cu

foil.



**Fig. S23** (a) Cross-sectional SEM image of PDMS/CuO/Cu foil. (b) SEM image of

the CuO micro-/nanostructure in CuO/Cu foil.



**Fig. S24** Corresponding infrared images over time of the PDMS/CuO/Cu foil,

CuO/Cu foil, and Cu foil. (Scale bar: 1 cm)



**Fig. S25** Panoramic view of the information interaction with the heat sensor of the organohydrogel based on Morse Code.



**Fig. S26** Wireless Bluetooth transmission device.

<b>Morse codes</b>							
А	$\bullet$ ▅	N	. .		0		
в	$\bullet$	O	▅		1	٠	
С	. .	P	ॱ∙		$\mathbf 2$	$\bullet$	
D	$\bullet\bullet$	Q			3	▅	
Е	$\bullet$	R	▪● $\bullet$		4	$\bullet$ ▄	
F	∙	S	$\bullet$ $\bullet$		5	$\ddot{\phantom{1}}$	
G	- •	T	▄		6	.	
Н	$\bullet$ $\bullet$	U	$\bullet$ $\blacksquare$ $\blacksquare$		7	$\bullet$	
ı	$\bullet\bullet$	v	▅ .		8		
J		W			9		
Κ	۰	X	$\overline{\phantom{0}}$				
L	$\bullet$	Υ	▀				
Μ		z					

**Fig. S27** International Morse Code table.



**Fig. S28** All letters in the international Morse Code table are indicated. (a) A-G,

(b) H-M, (c) N-T, (d) U-Z, (e) 0-4, (f) 5-9.



**Fig. S29** (a) Photos of the greenhous model. (b) Infrared image of the greenhouse model.



**Fig. S30** PDMS/CuO/Cu foil temperature at different optical densities.



**Fig. S31** Photographs of the contact angle tests for hydrophilic and hydrophobic features of Cu foil (a, b), CuO/Cu foil (c, d), and PDMS/CuO/Cu foil (e, f).



**Fig. S32** Output current and output voltage of different number of integrated devices

(a) in parallel and (b) in series.



**Fig. S33** Output voltage and winter light intensity changing throughout a day.

<b>Stress</b> (kPa)	Stretchability $(\%)$	$ S_e $ $(mV K^{-1})$		Recyclability Anti-freezing	Ref.
710	325	1.19	Yes	Yes	This work
97	420	0.63	Yes	Yes	1
260	356	1.43	N <sub>o</sub>	N <sub>o</sub>	$\overline{2}$
9	95	1.25	N <sub>o</sub>	N <sub>o</sub>	3
73	225	1.46	Yes	N <sub>o</sub>	$\overline{4}$
10.5	500	1.57	N <sub>o</sub>	No	5

Table S1. A comprehensive comparison between the organohydrogel and the previously reported thermogalvanic hydrogels in terms of the comprehensive properties of stress (kPa), stretchability (%), Seebeck coefficient ( $S_e$ ), recyclability and anti-freezing.



Table S2. Summary of the absorber materials, electricity type, solar intensity, and cost reported and this work.

**Photothermal conversion efficiency calculation.<sup>11</sup>** The overall steam generation efficiency  $(\eta)$  can be calculated using the Equation (1).

Equation (1):

 $\eta = (\dot{m} h_{IV})/q_i$ 

Where  $\dot{m}$  is the solar-driven evaporation rate of water under solar illumination,

 $q_i$  is the incident power density of solar illumination in process of steam generation experiment, and  $h_{LV}$  made up of the sensible heat and the enthalpy of vaporization is calculated using the Equation (2).

Equation (2):

 $h_{IV} = C\Delta T + \Delta h$ 

Where C is the specific heat capacity of water and a constant of 4.18 J  $g^{-1}K^{-1}$ ,  $\Delta T$ is the temperature increase of water, and ∆h is the enthalpy of vaporization on the relative temperature.

Supplemental references:

- 1 X. Li, X. Xiao, C. Bai, M. Mayer, X. Cui, K. Lin, Y. Li, H. Zhang and J. Chen, J. Mater. Chem. C, 2022, **10**, 13789-13796.
- 2 P. Peng, J. Zhou, L. Liang, X. Huang, H. Lv, Z. Liu and G. Chen, Nano-Micro Lett., 2022, **14**, 81.
- 3 Y. Zhou, S. Zhang, M. A. Buckingham, L. Aldous, S. Beirne, C. Wu, Y. Liu, G. Wallace and J. Chen, Chem. Eng. J., 2022, **449**, 137775.
- 4 H. Yang, S. Ahmed Khan, N. Li, R. Fang, Z. Huang and H. Zhang, Chem. Eng. J., 2023, **473**, 145247.
- 5 J. Shen, Y. Ma, C. Yang, S. Liu, J. Li, Z. Chen, B. Tian and S. Li, J. Mater. Chem. A, 2022, **10**, 7785-7791.
- 6 X. Li, X. Min, J. Li, N. Xu, P. Zhu, B. Zhu, S. Zhu and J. Zhu, Joule, 2018, **2**, 2477- 2484.
- 7 L. Zhu, M. Gao, C. K. N. Peh, X. Wang and G. W. Ho, Adv. Energy Mater., 2018, **8**, 1702149.
- 8 P. Yang, K. Liu, Q. Chen, J. Li, J. Duan, G. Xue, Z. Xu, W. Xie and J. Zhou, Energy Environ. Sci., 2017, **10**, 1923-1927.
- 9 N. Xu, P. Zhu, Y. Sheng, L. Zhou, X. Li, H. Tan, S. Zhu and J. Zhu, Joule, 2020, **4**, 347-358.
- 10 S. Meng, C. Tang, J. Yang, M. Yang and W. Yang, Adv. Sci., 2022, **9**, 2204187.
- 11 F. L. Meng, M. Gao, T. Ding, G. Yilmaz, W. L. Ong and G. W. Ho, Adv. Funct. Mater., 2020, **30**, 2002867.